Qualcom

RF360 Europe GmbH

Data sheet

SAW RF uplink filter Base stations LTE band 25

Part number:	B5609
Ordering code:	B39192B5609U410
Date:	May 27, 2020
Version:	2.3

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Table of contents

1 Application	4
2 <u>Features</u>	4
3 Package	5
4 Pin configuration	5
5 Matching circuit	6
6 Characteristics	7
7 Maximum ratings	8
8 <u>Transmission coefficient</u>	9
9 Reflection coefficients	10
10 Packing material.	
11 Marking	14
12 Soldering profile.	
13 Annotations	
14 <u>Cautions and warnings</u>	
15 Important notes.	

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1 Application

- LTE band 25 uplink: 1882.5 MHz (pass band 65 MHz)
- No external matching components required

2 Features

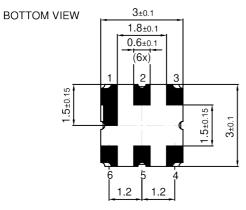
- Package code DCC6C
- Package size 3.0±0.1 mm × 3.0±0.1 mm
- Package height 1.1±0.125 mm
- Approximate weight 0.04 g
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Lead free soldering compatible with J-STD20C
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 1 (MSL1)



Figure 1: Picture of component with example of product marking.



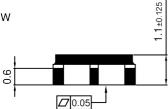
3 Package



4 Pin configuration

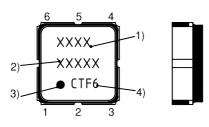
- 2 Input
- 5 Output
- 1, 3, 4, 6 Ground





TOP VIEW

SIDE VIEW



Device designation
 Last five digits of the lot number
 Marking for pad number 1
 Example of production location and date code

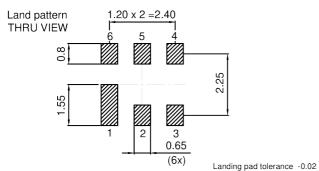


Figure 2: Drawing of package. See Sec. Package information (p. 17).

Please read **Cautions and warnings** and **Important notes** at the end of this document.



5 Matching circuit

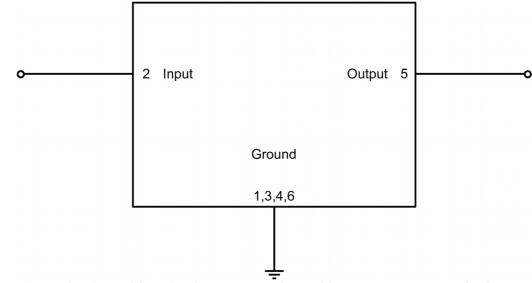


Figure 3: Schematic of matching circuit. No external matching components required.

6 Characteristics

Temperature range for specification	T _{SPEC}	= -40 °C +105 °C
Input terminating impedance	Z	= 50 Ω
Output terminating impedance	Z _{OUT}	= 50 Ω

Characteristics				min. for T _{SPEC}	typ. @ +25 °C	max. for $T_{\rm SPEC}$	
Center frequency			f _c	_	1882.5	_	MHz
Maximum insertion attenuation			α _{max}				
	1850 1915	MHz		_	2.4	4.0	dB
Amplitude ripple (p-p)			Δα				
	1850 1915	MHz		—	1.2	2.5	dB
Maximum VSWR			VSWR				
@ input port	1850 1915	MHz			1.7	2.5	
@ output port	1850 1915	MHz		—	1.7	2.5	
Minimum attenuation			$\alpha_{_{min}}$				
	10 450	MHz		35	40	_	dB
	450 1815	MHz		30	36	—	dB
	1815 1830	MHz		15	35	—	dB
	1930 1935	MHz		35 ¹⁾	49	—	dB
	1930 1935	MHz		20	49	—	dB
	1935 1970	MHz		40	50	—	dB
	1970 1995	MHz		37	45	—	dB
	1995 2250	MHz		30	43	_	dB
	2250 2280	MHz		15	40	—	dB
	2280 2450	MHz		5	15	—	dB
	2450 3800	MHz		20	29	—	dB
	3800 5000	MHz		10	16	—	dB

¹⁾ Valid for temperature T = -10 °C...+105 °C.

7 **Maximum ratings**

Operable temperature	<i>T</i> _{OP} = -40 °C +105 °C	
Storage temperature	$T_{\rm STG}^{1)} = -40 ^{\circ}{\rm C} \dots +105 ^{\circ}{\rm C}$	
DC voltage	$ V_{\rm DC} ^{2)} = 0 V$	
ESD voltage		
	$V_{\rm ESD}^{3)} = 250 \rm V$	Human body model.
	$V_{\rm ESD}^{4)} = 150 \rm V$	Machine model.
Input power	P _{IN}	
@ input port: 1850 1915 MHz	23 dBm	Continuous wave for 24 h @ 105 °C.
@ input port: 1850 1915 MHz	16 dBm	Continuous wave for 100000 h @ 105 °C.

1) Not valid for packaging material. Please refer to definition of Shelf life (p. 16).

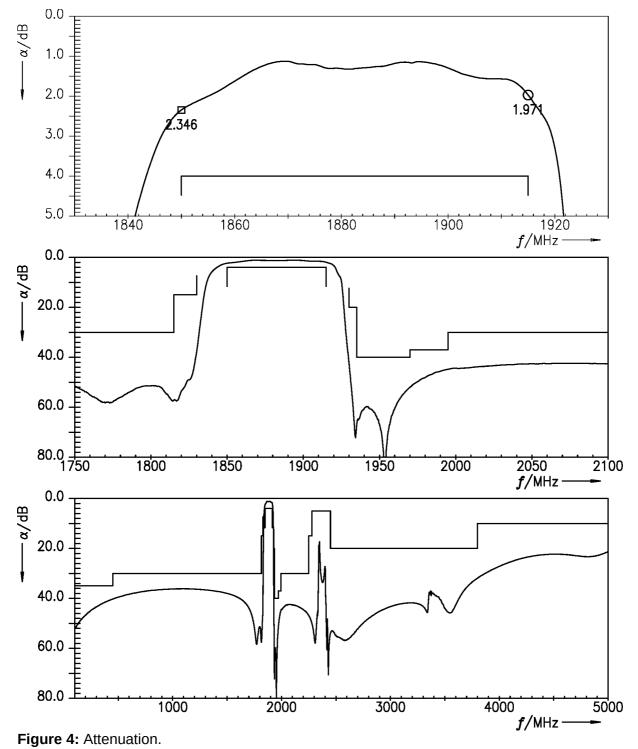
2)

In case of applied DC voltage blocking capacitors are mandatory. According to JESD22-A114F (HBM – Human Body Model), 1 negative & 1 positive pulse. According to JESD22-A115B (MM – Machine Model), 10 negative & 10 positive pulses. 3)

4)



8 Transmission coefficient





□ = 1850.0 O = 1915.0

Z_{IN}=50 Ω

9 Reflection coefficients

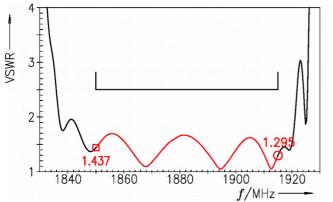
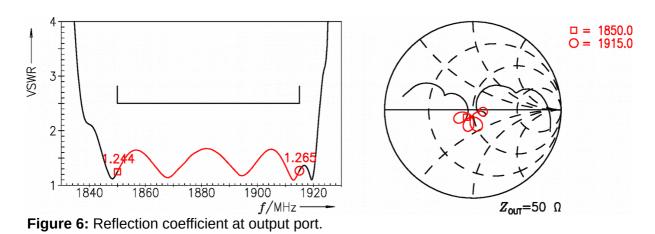


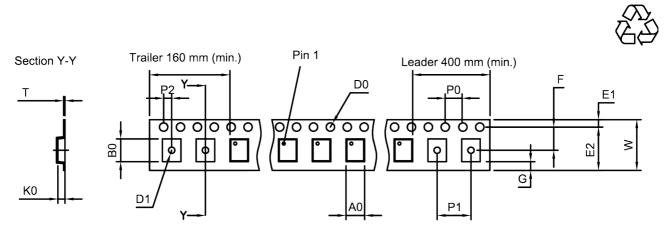
Figure 5: Reflection coefficient at input port.





10 Packing material

10.1 Tape



User direction of unreeling

Figure 7: Drawing of tape (first-angle projection) for illustration only and not to scale. The valid tape dimensions are listed in Table 1.

 $\begin{array}{c} A_0 \\ B_0 \\ 3.3 \pm 0.1 \text{ mm} \\ B_0 \\ 1.5 \pm 0.1 / -0 \text{ mm} \\ D_1 \\ 1.5 \text{ mm (min.)} \\ E_1 \\ 1.75 \pm 0.1 \text{ mm} \end{array}$

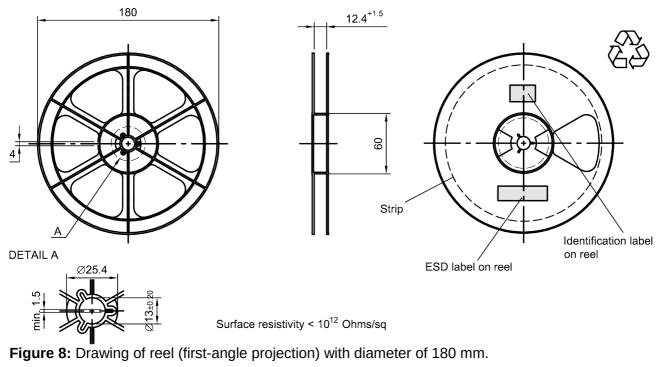
Table 1: Tape dimensions.

E ₂	10.25 mm (min.)
F	5.5±0.05 mm
G	0.75 mm (min.)
K ₀	1.5±0.1 mm
P_0	4.0±0.1 mm

P ₁	4.0±0.1 mm
P ₂	2.0±0.1 mm
Т	0.3±0.05 mm
W	12.0+0.3/-0.1 mm



10.2 Reel with diameter of 180 mm



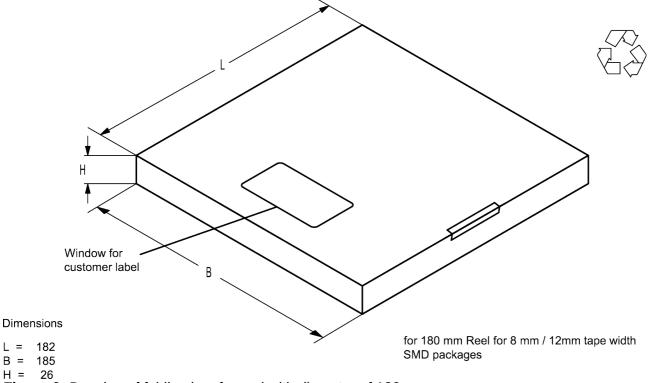
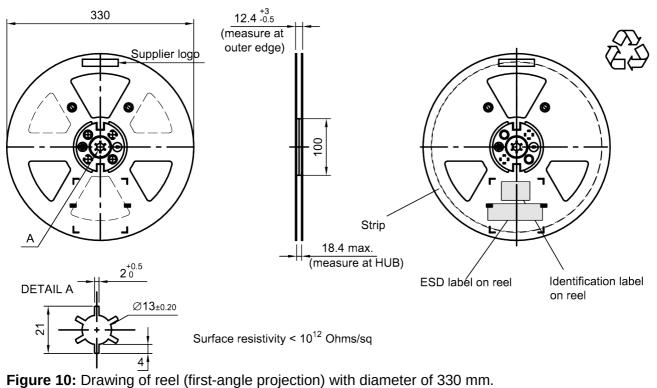


Figure 9: Drawing of folding box for reel with diameter of 180 mm.



10.3 Reel with diameter of 330 mm



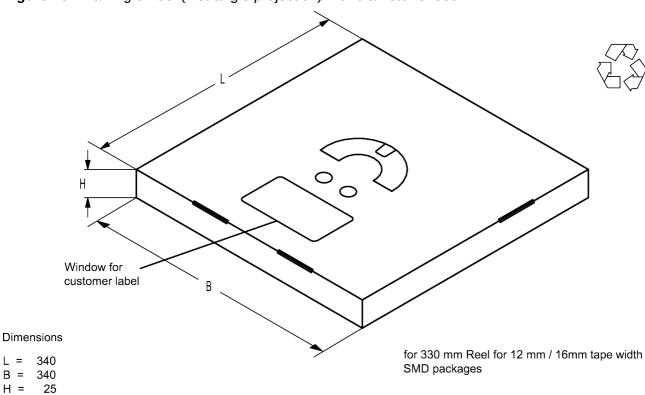


Figure 11: Drawing of folding box for reel with diameter of 330 mm.

11 Marking

Products are marked with device designation, lot number, as well as production location and date code.

Device designation: The 4-character device designation of the ordering code is used for the marking.

Example for 4-character device designation: B3xxxxB1234xxxx

■ Lot number: The last 5 digits of the lot number are used for the marking.

Example: 12345

Production location and date code: The production location is Wuxi (encoded in the first character 'C'). The production date code is encoded in the last three characters according to Table 2.

	1 st digit (day)					2 nd digit (year)				3 rd digit	(month)		
Day	Code	Day	Code	Day	Code	Year	Code	Year	Code	Month	Code	Month	Code
1	1	11	А	21	М	2010	А	2022	Р	Jan	1	Jul	7
2	2	12	В	22	N	2011	В	2023	R	Feb	2	Aug	8
3	3	13	С	23	Р	2012	С	2024	S	Mar	3	Sep	9
4	4	14	D	24	R	2013	D	2025	Т	Apr	4	Oct	0
5	5	15	E	25	S	2014	Е	2026	U	Мау	5	Nov	N
6	6	16	F	26	Т	2015	F	2027	V	Jun	6	Dec	D
7	7	17	н	27	U	2016	Н	2028	W				
8	8	18	J	28	V	2017	J	2029	Х				
9	9	19	к	29	W	2018	К	2030	Z				
10	0	20	L	30	Х	2019	L	2031	Α				
				31	Z	2020	М	2032	В				
						2021	Ν	and	so on				

 Table 2: Production date code.

Example of how to decode production location and date code:

Code:	C T F 6

Location:	С	\rightarrow	Wuxi
Day:	Т	\rightarrow	26 th
Year:	F	\rightarrow	2015
Month:	6	\rightarrow	June

12 Soldering profile

The recommended soldering process is in accordance with IEC 60068-2-58 – 3^{rd} edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
<i>T</i> > 220 °C	30 s to 70 s
<i>T</i> > 230 °C	min. 10 s
<i>T</i> > 245 °C	max. 20 s
<i>T</i> ≥ 255 °C	_
peak temperature T _{peak}	250 °C +0/-5 °C
wetting temperature T_{min}	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature T	measured at solder pads

 Table 3: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).

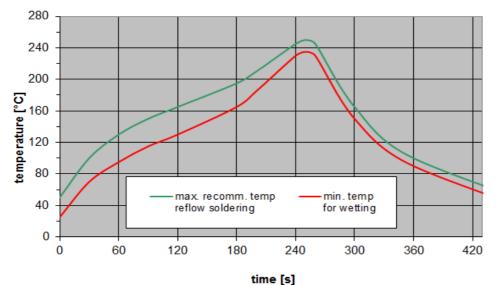


Figure 12: Recommended reflow profile for convection and infrared soldering – lead-free solder.

13 Annotations

13.1 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

13.2 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

13.3 Shelf life

The shelf life of components is determined by solderability of the package terminals. It is specified as 2 years from manufacturing date assuming the following conditions:

- storage in original packaging and non-aggressive atmosphere,
- storage temperature ranging from -25 °C to +40 °C, and
- storage humidity with \leq 75 % r.h. mean annual humidity, \leq 95 % r.h. for max. 30 days / year, and no dew condensation.

13.4 Ordering codes and packing units

Ordering code	Packing unit
B39192B5609U410	9000 pcs
B39192B5609U410W 3	3000 pcs

Table 4: Ordering codes and packing units.

14 Cautions and warnings

14.1 Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under https://rffe.qualcomm.com/.

14.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

14.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

14.4 Package information

Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Projection method

Unless otherwise specified first-angle projection is applied.



15 Important notes

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- 2. We also point out that in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified. In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
- 3. The warnings, cautions and product-specific notes must be observed.
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